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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	3000
Total RAM Bits	55296
Number of I/O	100
Number of Gates	-
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	144-LQFP
Supplier Device Package	144-TQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp3e-3tn144c

Architecture Overview

The LatticeXP architecture contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM Embedded Block RAM (EBR) as shown in Figure 2-1.

On the left and right sides of the PFU array, there are Non-volatile Memory Blocks. In configuration mode this non-volatile memory is programmed via the IEEE 1149.1 TAP port or the sysCONFIG™ peripheral port. On power up, the configuration data is transferred from the Non-volatile Memory Blocks to the configuration SRAM. With this technology, expensive external configuration memories are not required and designs are secured from unauthorized read-back. This transfer of data from non-volatile memory to configuration SRAM via wide busses happens in microseconds, providing an “instant-on” capability that allows easy interfacing in many applications.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and Programmable Functional unit without RAM/ROM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM and register functions. The PFF block contains building blocks for logic, arithmetic and ROM functions. Both PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and efficiently. Logic Blocks are arranged in a two-dimensional array. Only one type of block is used per row. The PFU blocks are used on the outside rows. The rest of the core consists of rows of PFF blocks interspersed with rows of PFU blocks. For every three rows of PFF blocks there is a row of PFU blocks.

Each PIC block encompasses two PIOs (PIO pairs) with their respective sysIO interfaces. PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs. sysMEM EBRs are large dedicated fast memory blocks. They can be configured as RAM or ROM.

The PFU, PFF, PIC and EBR Blocks are arranged in a two-dimensional grid with rows and columns as shown in Figure 2-1. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

At the end of the rows containing the sysMEM Blocks are the sysCLOCK Phase Locked Loop (PLL) Blocks. These PLLs have multiply, divide and phase shifting capability; they are used to manage the phase relationship of the clocks. The LatticeXP architecture provides up to four PLLs per device.

Every device in the family has a JTAG Port with internal Logic Analyzer (ispTRACY) capability. The sysCONFIG port which allows for serial or parallel device configuration. The LatticeXP devices are available for operation from 3.3V, 2.5V, 1.8V and 1.2V power supplies, providing easy integration into the overall system.

in selected blocks the input to the DQS delay block. If one of the bypass options is not chosen, the signal first passes through an optional delay block. This delay, if selected, ensures no positive input-register hold-time requirement when using a global clock.

The input block allows two modes of operation. In the single data rate (SDR) the data is registered, by one of the registers in the single data rate sync register block, with the system clock. In the DDR Mode two registers are used to sample the data on the positive and negative edges of the DQS signal creating two data streams, D0 and D2. These two data streams are synchronized with the system clock before entering the core. Further discussion on this topic is in the DDR Memory section of this data sheet.

Figure 2-21 shows the input register waveforms for DDR operation and Figure 2-22 shows the design tool primitives. The SDR/SYNC registers have reset and clock enable available.

The signal DDRCLKPOL controls the polarity of the clock used in the synchronization registers. It ensures adequate timing when data is transferred from the DQS to the system clock domain. For further discussion of this topic, see the DDR memory section of this data sheet.

Figure 2-20. Input Register Diagram

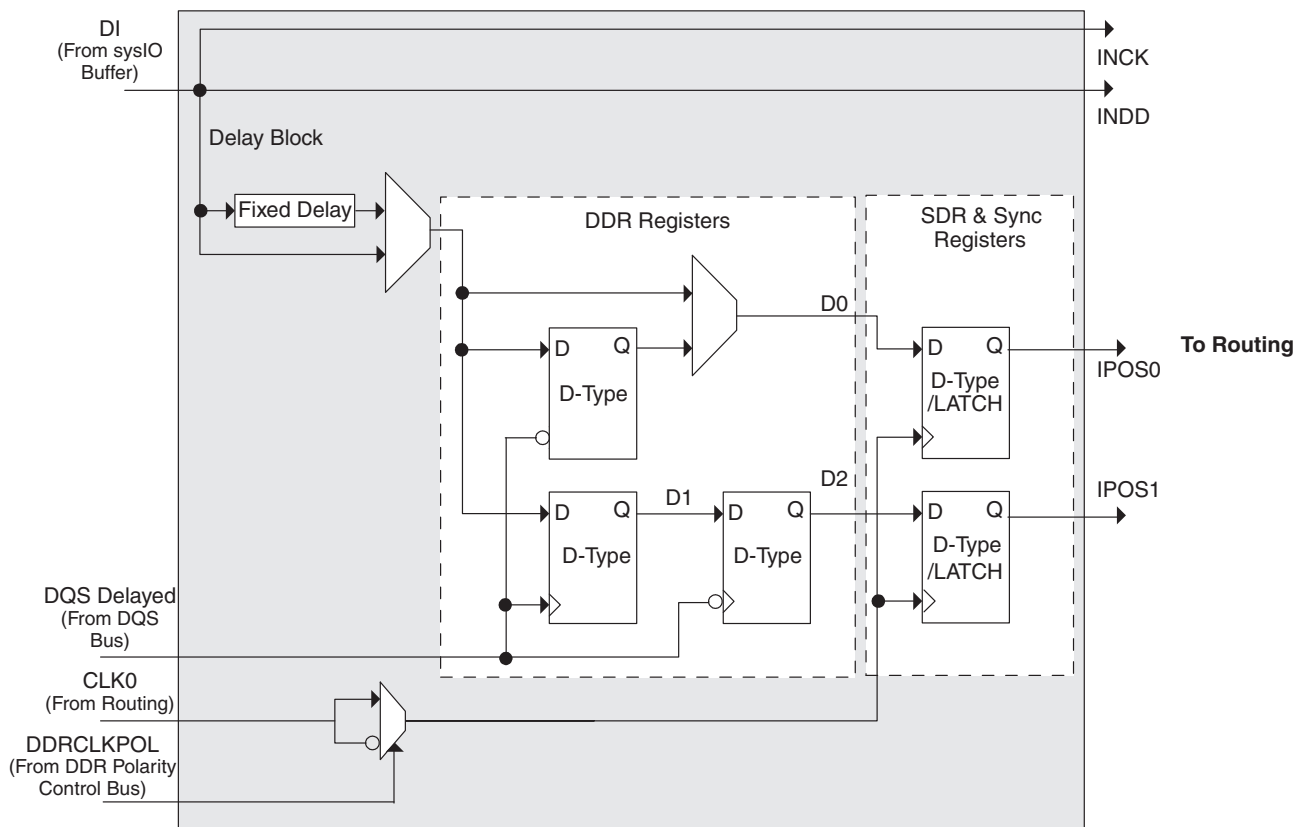
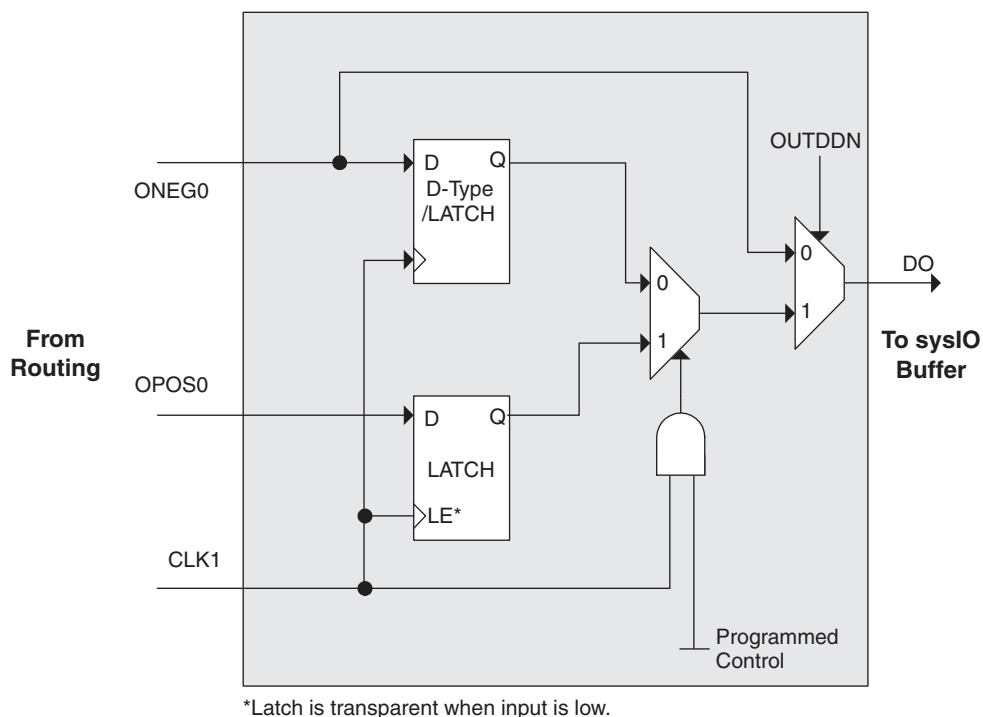
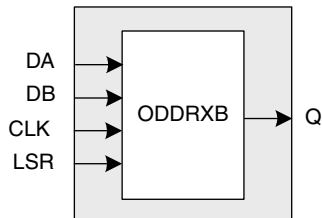
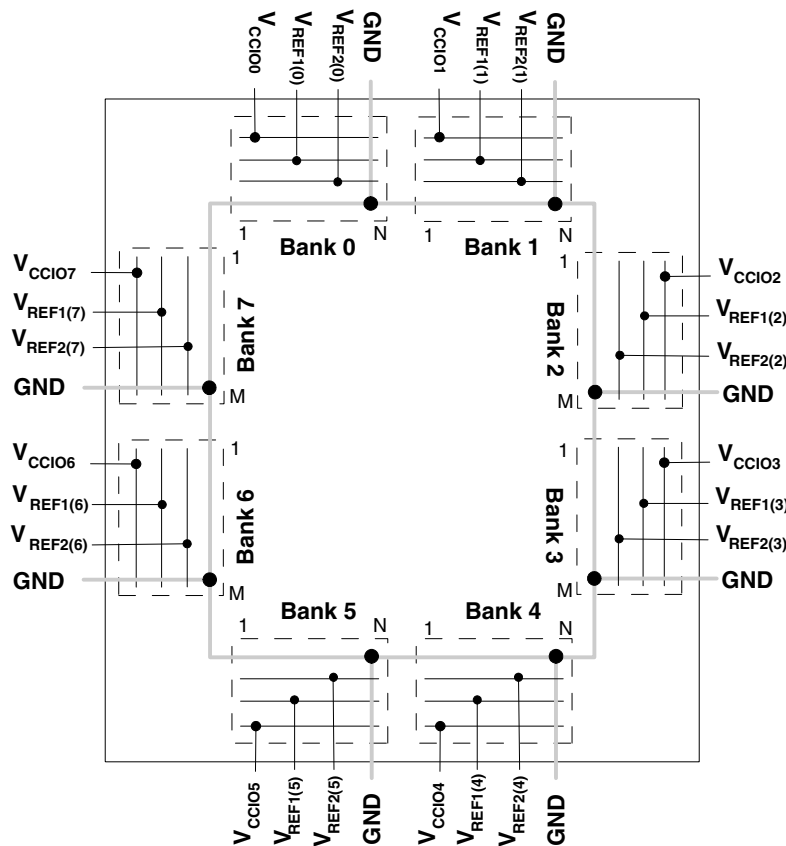


Figure 2-23. Output Register Block**Figure 2-24. ODDRXB Primitive****Tristate Register Block**

The tristate register block provides the ability to register tri-state control signals from the core of the device before they are passed to the sysIO buffers. The block contains a register for SDR operation and an additional latch for DDR operation. Figure 2-25 shows the diagram of the Tristate Register Block.

In SDR mode, ONEG1 feeds one of the flip-flops that then feeds the output. The flip-flop can be configured a D-type or latch. In DDR mode, ONEG1 is fed into one register on the positive edge of the clock and OPOS1 is latched. A multiplexer running off the same clock selects the correct register for feeding to the output (D0).

Figure 2-28. LatticeXP Banks



Note: N and M are the maximum number of I/Os per bank.

LatticeXP devices contain two types of sysIO buffer pairs.

1. **Top and Bottom sysIO Buffer Pair (Single-Ended Outputs Only)**

The sysIO buffer pairs in the top and bottom banks of the device consist of two single-ended output drivers and two sets of single-ended input buffers (both ratioed and referenced). The referenced input buffer can also be configured as a differential input.

The two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential input buffer and the comp (complementary) pad is associated with the negative side of the differential input buffer.

Only the I/Os on the top and bottom banks have PCI clamps. Note that the PCI clamp is enabled after V_{CC} , V_{CCAUX} and V_{CCIO} are at valid operating levels and the device has been configured.

2. **Left and Right sysIO Buffer Pair (Differential and Single-Ended Outputs)**

The sysIO buffer pairs in the left and right banks of the device consist of two single-ended output drivers, two sets of single-ended input buffers (both ratioed and referenced) and one differential output driver. The referenced input buffer can also be configured as a differential input. In these banks the two pads in the pair are described as “true” and “comp”, where the true pad is associated with the positive side of the differential I/O, and the comp (complementary) pad is associated with the negative side of the differential I/O.

Select I/Os in the left and right banks have LVDS differential output drivers. Refer to the Logic Signal Connections tables for more information.

Table 2-8. Supported Output Standards

Output Standard	Drive	V _{CCIO} (Nom.)
Single-ended Interfaces		
LVTTL	4mA, 8mA, 12mA, 16mA, 20mA	3.3
LVC MOS33	4mA, 8mA, 12mA 16mA, 20mA	3.3
LVC MOS25	4mA, 8mA, 12mA 16mA, 20mA	2.5
LVC MOS18	4mA, 8mA, 12mA 16mA	1.8
LVC MOS15	4mA, 8mA	1.5
LVC MOS12	2mA, 6mA	1.2
LVC MOS33, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVC MOS25, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVC MOS18, Open Drain	4mA, 8mA, 12mA 16mA	—
LVC MOS15, Open Drain	4mA, 8mA	—
LVC MOS12, Open Drain	2mA, 6mA	—
PCI33	N/A	3.3
HSTL18 Class I, II, III	N/A	1.8
HSTL15 Class I, III	N/A	1.5
SSTL3 Class I, II	N/A	3.3
SSTL2 Class I, II	N/A	2.5
SSTL18 Class I	N/A	1.8
Differential Interfaces		
Differential SSTL3, Class I, II	N/A	3.3
Differential SSTL2, Class I, II	N/A	2.5
Differential SSTL18, Class I	N/A	1.8
Differential HSTL18, Class I, II, III	N/A	1.8
Differential HSTL15, Class I, III	N/A	1.5
LVDS	N/A	2.5
BLVDS ¹	N/A	2.5
LVPECL ¹	N/A	3.3

1. Emulated with external resistors.

Hot Socketing

The LatticeXP devices have been carefully designed to ensure predictable behavior during power-up and power-down. Power supplies can be sequenced in any order. During power up and power-down sequences, the I/Os remain in tristate until the power supply voltage is high enough to ensure reliable operation. In addition, leakage into I/O pins is controlled to within specified limits, which allows easy integration with the rest of the system. These capabilities make the LatticeXP ideal for many multiple power supply and hot-swap applications.

Sleep Mode

The LatticeXP “C” devices (V_{CC} = 1.8/2.5/3.3V) have a sleep mode that allows standby current to be reduced by up to three orders of magnitude during periods of system inactivity. Entry and exit to Sleep Mode is controlled by the SLEEPN pin.

During Sleep Mode, the FPGA logic is non-operational, registers and EBR contents are not maintained and I/Os are tri-stated. Do not enter Sleep Mode during device programming or configuration operation. In Sleep Mode, power supplies can be maintained in their normal operating range, eliminating the need for external switching of power supplies. Table 2-9 compares the characteristics of Normal, Off and Sleep Modes.

Differential HSTL and SSTL

Differential HSTL and SSTL outputs are implemented as a pair of complementary single-ended outputs. All allowable single-ended output classes (class I and class II) are supported in this mode.

LVDS25E

The top and bottom side of LatticeXP devices support LVDS outputs via emulated complementary LVCMOS outputs in conjunction with a parallel resistor across the driver outputs. The scheme shown in Figure 3-1 is one possible solution for point-to-point signals.

Figure 3-1. LVDS25E Output Termination Example

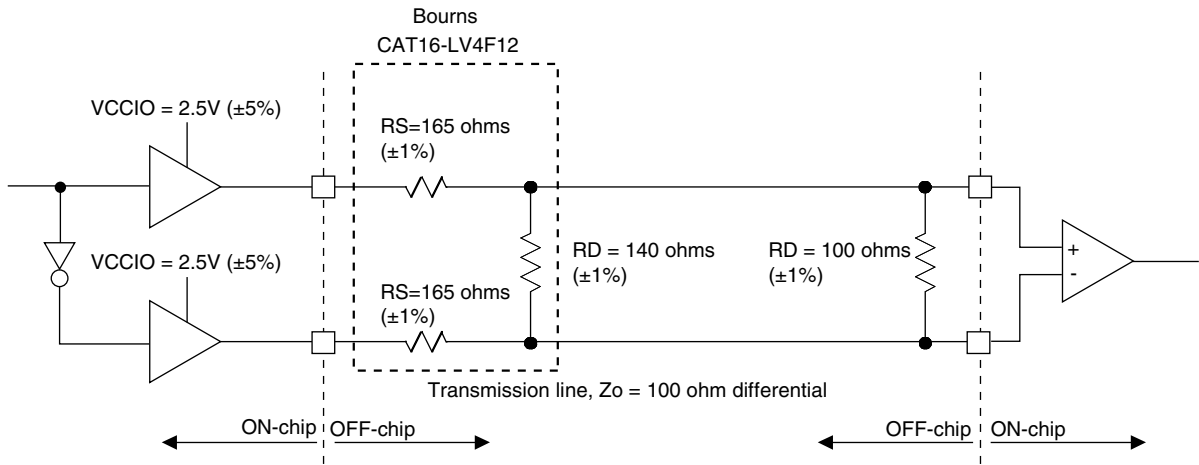


Table 3-1. LVDS25E DC Conditions

Over Recommended Operating Conditions			
Parameter	Description	Typical	Units
V_{OH}	Output high voltage	1.43	V
V_{OL}	Output low voltage	1.07	V
V_{OD}	Output differential voltage	0.35	V
V_{CM}	Output common mode voltage	1.25	V
Z_{BACK}	Back impedance	100	ohms
I_{DC}	DC output current	3.66	mA

BLVDS

The LatticeXP devices support BLVDS standard. This standard is emulated using complementary LVCMOS outputs in conjunction with a parallel external resistor across the driver outputs. BLVDS is intended for use when multi-drop and bi-directional multi-point differential signaling is required. The scheme shown in Figure 3-2 is one possible solution for bi-directional multi-point differential signals.

Typical Building Block Function Performance¹**Pin-to-Pin Performance (LVCMOS25 12 mA Drive)**

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	6.1	ns
32-bit decoder	7.3	ns
64-bit decoder	8.2	ns
4:1 MUX	4.9	ns
8:1 MUX	5.3	ns
16:1 MUX	5.7	ns
32:1 MUX	6.3	ns

Register to Register Performance

Function	-5 Timing	Units
Basic Functions		
16-bit decoder	351	MHz
32-bit decoder	248	MHz
64-bit decoder	237	MHz
4:1 MUX	590	MHz
8:1 MUX	523	MHz
16:1 MUX	434	MHz
32:1 MUX	355	MHz
8-bit adder	343	MHz
16-bit adder	292	MHz
64-bit adder	130	MHz
16-bit counter	388	MHz
32-bit counter	295	MHz
64-bit counter	200	MHz
64-bit accumulator	164	MHz
Embedded Memory Functions		
Single Port RAM 256x36 bits	254	MHz
True-Dual Port RAM 512x18 bits	254	MHz
Distributed Memory Functions		
16x2 SP RAM	434	MHz
64x2 SP RAM	332	MHz
128x4 SP RAM	235	MHz
32x2 PDP RAM	322	MHz
64x4 PDP RAM	291	MHz

1. These timing numbers were generated using the ispLEVER design tool. Exact performance may vary with design and tool version. The tool uses internal parameters that have been characterized but are not tested on every device.

Timing v.F0.11

Derating Logic Timing

Logic timing provided in the following sections of this data sheet and in the ispLEVER design tools are worst case numbers in the operating range. Actual delays at nominal temperature and voltage for best-case process can be much better than the values given in the tables. The ispLEVER design tool from Lattice can provide logic timing numbers at a particular temperature and voltage.

LatticeXP Internal Timing Parameters¹ (Continued)

Over Recommended Operating Conditions

Parameter	Description	-5		-4		-3		Units
		Min.	Max.	Min.	Max.	Min.	Max.	
t_{RSTO_EBR}	Reset To Output Delay Time from EBR Output Register	—	1.61	—	1.94	—	2.32	ns
PLL Parameters								
t_{RSTREC}	Reset Recovery to Rising Clock	1.00	—	1.00	—	1.00	—	ns
t_{RSTSU}	Reset Signal Setup Time	1.00	—	1.00	—	1.00	—	ns

1. Internal parameters are characterized but not tested on every device.
Timing v.F0.11

Signal Descriptions (Cont.)

Signal Name	I/O	Descriptions
Test and Programming (Dedicated pins. Pull-up is enabled on input pins during configuration.)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data in pin, used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence).
TDO	O	Output pin -Test Data out pin used to shift data out of device using 1149.1.
V _{CCJ}	—	V _{CCJ} - The power supply pin for JTAG Test Access Port.
Configuration Pads (used during sysCONFIG)		
CFG[1:0]	I	Mode pins used to specify configuration modes values latched on rising edge of INITN. During configuration, a pull-up is enabled.
INITN	I/O	Open Drain pin - Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled. If CFG1 and CFG0 are high (SDM) then this pin is pulled low.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up.
DONE	I/O	Open Drain pin - Indicates that the configuration sequence is complete, and the startup sequence is in progress.
CCLK	I/O	Configuration Clock for configuring an FPGA in sysCONFIG mode.
BUSY	I/O	Generally not used. After configuration it is a user-programmable I/O pin.
CSN	I	sysCONFIG chip select (Active low). During configuration, a pull-up is enabled. After configuration it is user a programmable I/O pin.
CS1N	I	sysCONFIG chip select (Active Low). During configuration, a pull-up is enabled. After configuration it is user programmable I/O pin
WRITEN	I	Write Data on Parallel port (Active low). After configuration it is a user programmable I/O pin
D[7:0]	I/O	sysCONFIG Port Data I/O. After configuration these are user programmable I/O pins.
DOUT, CSON	O	Output for serial configuration data (rising edge of CCLK) when using sysCONFIG port. After configuration, it is a user-programmable I/O pin.
DI	I	Input for serial configuration data (clocked with CCLK) when using sysCONFIG port. During configuration, a pull-up is enabled. After configuration it is a user-programmable I/O pin.
SLEEPN ²	I	Sleep Mode pin - Active low sleep pin. p When this pin is held high, the device operates normally. p When driven low, the device moves into Sleep Mode after a specified time. This pin has a weak internal pull-up, but when not used an external pull-up to V _{CC} is recommended.
TOE ³	I	Test Output Enable tri-states all I/O pins when driven low. This pin has a weak internal pull-up, but when not used an external pull-up to V _{CC} is recommended.

1. Applies to LFXP10, LFXP15 and LFXP20 only.

2. Applies to LFXP "C" devices only.

3. Applies to LFXP "E" devices only.

Pin Information Summary¹ (Cont.)

Pin Type		XP10		XP15			XP20		
		256 fpBGA	388 fpBGA	256 fpBGA	388 fpBGA	484 fpBGA	256 fpBGA	388 fpBGA	484 fpBGA
Single Ended User I/O		188	244	188	268	300	188	268	340
Differential Pair User I/O ²		76	104	76	112	128	76	112	144
Configuration	Dedicated	11	11	11	11	11	11	11	11
	Muxed	14	14	14	14	14	14	14	14
TAP		5	5	5	5	5	5	5	5
Dedicated (total without supplies)		6	6	6	6	6	6	6	6
V _{CC}		8	14	8	14	28	8	14	28
V _{CCAUX}		4	4	4	4	12	4	4	12
V _{CCPLL}		2	2	2	2	2	2	2	2
V _{CCIO}	Bank0	2	5	2	5	4	2	5	4
	Bank1	2	5	2	5	4	2	5	4
	Bank2	2	4	2	4	4	2	4	4
	Bank3	2	4	2	4	4	2	4	4
	Bank4	2	5	2	5	4	2	5	4
	Bank5	2	5	2	5	4	2	5	4
	Bank6	2	4	2	4	4	2	4	4
	Bank7	2	4	2	4	4	2	4	4
GND		24	50	24	50	56	24	50	56
GND _{PLL}		2	2	2	2	2	2	2	2
NC		0	24	0	0	40	0	0	0
Single Ended/ Differential I/O per Bank ²	Bank0	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank1	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank2	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
	Bank3	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
	Bank4	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank5	26/11	33/14	26/11	39/16	40/17	26/11	39/16	47/20
	Bank6	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
	Bank7	21/8	28/12	21/8	28/12	35/15	21/8	28/12	38/16
V _{CCJ}		1	1	1	1	1	1	1	1

1. During configuration the user-programmable I/Os are tri-stated with an internal pull-up resistor enabled. If any pin is not used (or not bonded to a package pin), it is also tri-stated with an internal pull-up resistor enabled after configuration.
2. The differential I/O per bank includes both dedicated LVDS and emulated LVDS pin pairs. Please see the Logic Signal Connections table for more information.

LFXP3 & LFXP6 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
93	PB19B	4	C	VREF1_4	PB22B	4	C	VREF1_4
94	PB20A	4	T	-	PB23A	4	T	-
95	PB20B	4	C	-	PB23B	4	C	-
96	PB21A	4	T	-	PB24A	4	T	-
97	VCCIO4	4	-	-	VCCIO4	4	-	-
98	PB21B	4	C	-	PB24B	4	C	-
99	PB22A	4	T	-	PB25A	4	T	-
100	PB22B	4	C	-	PB25B	4	C	-
101	PB23A	4	T	-	PB26A	4	T	-
102	PB23B	4	C	-	PB26B	4	C	-
103	PB24A	4	T	VREF2_4	PB27A	4	-	VREF2_4
104	PB24B	4	C	-	PB30A	4	T	DQS
105	PB25A	4	-	-	PB30B	4	C	-
106	GND	-	-	-	GND	-	-	-
107	VCC	-	-	-	VCC	-	-	-
108	PR18B	3	C ³	-	PR26B	3	C ³	-
109	GNDIO3	3	-	-	GNDIO3	3	-	-
110	PR18A	3	T ³	-	PR26A	3	T ³	-
111	PR17B	3	C	-	PR25B	3	C	-
112	PR17A	3	T	-	PR25A	3	T	-
113	PR16B	3	C ³	-	PR24B	3	C ³	-
114	PR16A	3	T ³	DQS	PR24A	3	T ³	DQS
115	VCCIO3	3	-	-	VCCIO3	3	-	-
116	PR15B	3	-	VREF1_3	PR23B	3	-	VREF1_3
117	PR14A	3	-	VREF2_3	PR22A	3	-	VREF2_3
118	GNDIO3	3	-	-	GNDIO3	3	-	-
119	PR13B	3	C	-	PR21B	3	C ³	-
120	PR13A	3	T	-	PR21A	3	T ³	-
121	GND	-	-	-	GND	-	-	-
122	PR12B	3	C	-	PR20B	3	C	-
123	PR12A	3	T	-	PR20A	3	T	-
124	PR11B	3	C	-	PR19B	3	C ³	-
125	VCCIO3	3	-	-	VCCIO3	3	-	-
126	PR11A	3	T	-	PR19A	3	T ³	-
127	GNDP1	-	-	-	GNDP1	-	-	-
128	VCCP1	-	-	-	VCCP1	-	-	-
129	NC	-	-	-	PR13A	2	-	-
130	GND	-	-	-	GND	-	-	-
131	PR9B	2	C	PCLKC2_0	PR12B	2	C	PCLKC2_0
132	PR9A	2	T	PCLKT2_0	PR12A	2	T	PCLKT2_0
133	NC	-	-	-	PR11B	2	C ³	-
134	NC	-	-	-	PR11A	2	T ³	-
135	GNDIO2	2	-	-	GNDIO2	2	-	-
136	PR8B	2	C	RUM0_PLLC_IN_A	PR8B	2	C	RUM0_PLLC_IN_A
137	PR8A	2	T	RUM0_PLLT_IN_A	PR8A	2	T	RUM0_PLLT_IN_A
138	PR7B	2	C ³	-	PR7B	2	C ³	-

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L4	PL32A	6	-	-	PL36A	6	-	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
K4	PL33A	6	T	-	PL37A	6	T	-
K5	PL33B	6	C	-	PL37B	6	C	-
N1	PL35A	6	-	VREF2_6	PL39A	6	-	VREF2_6
N2	PL36B	6	-	-	PL40B	6	-	-
P1	PL37A	6	T ³	DQS	PL41A	6	T ³	DQS
P2	PL37B	6	C ³	-	PL41B	6	C ³	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
L5	PL38A	6	T	LLM0_PLLT_FB_A	PL42A	6	T	LLM0_PLLT_FB_A
M6	PL38B	6	C	LLM0_PLLC_FB_A	PL42B	6	C	LLM0_PLLC_FB_A
M3	PL39A	6	T ³	-	PL43A	6	T ³	-
N3	PL39B	6	C ³	-	PL43B	6	C ³	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
P4	SLEEPN ¹ /TOE ²	-	-	-	SLEEPN ¹ /TOE ²	-	-	-
P3	INITN	5	-	-	INITN	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
R4	PB11A	5	T	-	PB15A	5	T	-
N5	PB11B	5	C	-	PB15B	5	C	-
P5	PB12A	5	T	VREF1_5	PB16A	5	T	VREF1_5
-	GNDIO5	5	-	-	GNDIO5	5	-	-
R1	PB12B	5	C	-	PB16B	5	C	-
N6	PB13A	5	-	-	PB17A	5	-	-
M7	PB14B	5	-	-	PB18B	5	-	-
R2	PB15A	5	T	DQS	PB19A	5	T	DQS
T2	PB15B	5	C	-	PB19B	5	C	-
R3	PB16A	5	T	-	PB20A	5	T	-
T3	PB16B	5	C	-	PB20B	5	C	-
T4	PB17A	5	T	-	PB21A	5	T	-
R5	PB17B	5	C	VREF2_5	PB21B	5	C	VREF2_5
N7	PB18A	5	T	-	PB22A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
M8	PB18B	5	C	-	PB22B	5	C	-
T5	PB19A	5	T	-	PB23A	5	T	-
P6	PB19B	5	C	-	PB23B	5	C	-
T6	PB20A	5	T	-	PB24A	5	T	-
R6	PB20B	5	C	-	PB24B	5	C	-
P7	PB21A	5	-	-	PB25A	5	-	-
N8	PB22B	5	-	-	PB26B	5	-	-
R7	PB23A	5	T	DQS	PB27A	5	T	DQS

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
G10	GND	-	-	-	GND	-	-	-
G7	GND	-	-	-	GND	-	-	-
G8	GND	-	-	-	GND	-	-	-
G9	GND	-	-	-	GND	-	-	-
H10	GND	-	-	-	GND	-	-	-
H7	GND	-	-	-	GND	-	-	-
H8	GND	-	-	-	GND	-	-	-
H9	GND	-	-	-	GND	-	-	-
J10	GND	-	-	-	GND	-	-	-
J7	GND	-	-	-	GND	-	-	-
J8	GND	-	-	-	GND	-	-	-
J9	GND	-	-	-	GND	-	-	-
K10	GND	-	-	-	GND	-	-	-
K7	GND	-	-	-	GND	-	-	-
K8	GND	-	-	-	GND	-	-	-
K9	GND	-	-	-	GND	-	-	-
L11	GND	-	-	-	GND	-	-	-
L6	GND	-	-	-	GND	-	-	-
T1	GND	-	-	-	GND	-	-	-
T16	GND	-	-	-	GND	-	-	-
D13	VCC	-	-	-	VCC	-	-	-
D4	VCC	-	-	-	VCC	-	-	-
E12	VCC	-	-	-	VCC	-	-	-
E5	VCC	-	-	-	VCC	-	-	-
M12	VCC	-	-	-	VCC	-	-	-
M5	VCC	-	-	-	VCC	-	-	-
N13	VCC	-	-	-	VCC	-	-	-
N4	VCC	-	-	-	VCC	-	-	-
E13	VCCAUX	-	-	-	VCCAUX	-	-	-
E4	VCCAUX	-	-	-	VCCAUX	-	-	-
M13	VCCAUX	-	-	-	VCCAUX	-	-	-
M4	VCCAUX	-	-	-	VCCAUX	-	-	-
F7	VCCIO0	0	-	-	VCCIO0	0	-	-
F8	VCCIO0	0	-	-	VCCIO0	0	-	-
F10	VCCIO1	1	-	-	VCCIO1	1	-	-
F9	VCCIO1	1	-	-	VCCIO1	1	-	-
G11	VCCIO2	2	-	-	VCCIO2	2	-	-
H11	VCCIO2	2	-	-	VCCIO2	2	-	-
J11	VCCIO3	3	-	-	VCCIO3	3	-	-
K11	VCCIO3	3	-	-	VCCIO3	3	-	-
L10	VCCIO4	4	-	-	VCCIO4	4	-	-
L9	VCCIO4	4	-	-	VCCIO4	4	-	-

LFXP10, LFXP15 & LFXP20 Logic Signal Connections: 388 fpBGA (Cont.)

Ball Number	LFXP10				LFXP15				LFXP20			
	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function	Ball Function	Bank	Diff.	Dual Function
C20	PT38A	1	T	-	PT43A	1	T	-	PT47A	1	T	-
C21	PT37B	1	C	-	PT42B	1	C	-	PT46B	1	C	-
C22	PT37A	1	T	-	PT42A	1	T	-	PT46A	1	T	-
B22	PT36B	1	C	-	PT41B	1	C	-	PT45B	1	C	-
A21	PT36A	1	T	-	PT41A	1	T	-	PT45A	1	T	-
D15	PT35B	1	C	-	PT40B	1	C	-	PT44B	1	C	-
D14	PT35A	1	T	-	PT40A	1	T	-	PT44A	1	T	-
B21	PT34B	1	C	VREF1_1	PT39B	1	C	VREF1_1	PT43B	1	C	VREF1_1
-	GNDIO1	1	-	-	GNDIO1	1	-	-	GNDIO1	1	-	-
A20	PT34A	1	T	DQS	PT39A	1	T	DQS	PT43A	1	T	DQS
B20	PT33B	1	-	-	PT38B	1	-	-	PT42B	1	-	-
A19	PT32A	1	-	-	PT37A	1	-	-	PT41A	1	-	-
B19	PT31B	1	C	-	PT36B	1	C	-	PT40B	1	C	-
A18	PT31A	1	T	-	PT36A	1	T	-	PT40A	1	T	-
C14	PT30B	1	C	-	PT35B	1	C	-	PT39B	1	C	-
C13	PT30A	1	T	D0	PT35A	1	T	D0	PT39A	1	T	D0
B18	PT29B	1	C	D1	PT34B	1	C	D1	PT38B	1	C	D1
A17	PT29A	1	T	VREF2_1	PT34A	1	T	VREF2_1	PT38A	1	T	VREF2_1
B17	PT28B	1	C	-	PT33B	1	C	-	PT37B	1	C	-
A16	PT28A	1	T	D2	PT33A	1	T	D2	PT37A	1	T	D2
-	GNDIO1	1	-	-	GNDIO1	1	-	-	GNDIO1	1	-	-
B16	PT27B	1	C	D3	PT32B	1	C	D3	PT36B	1	C	D3
A15	PT27A	1	T	-	PT32A	1	T	-	PT36A	1	T	-
B15	PT26B	1	C	-	PT31B	1	C	-	PT35B	1	C	-
A14	PT26A	1	T	DQS	PT31A	1	T	DQS	PT35A	1	T	DQS
D13	PT25B	1	-	-	PT30B	1	-	-	PT34B	1	-	-
D12	PT24A	1	-	D4	PT29A	1	-	D4	PT33A	1	-	D4
B14	PT23B	1	C	-	PT28B	1	C	-	PT32B	1	C	-
A13	PT23A	1	T	D5	PT28A	1	T	D5	PT32A	1	T	D5
-	GNDIO1	1	-	-	GNDIO1	1	-	-	GNDIO1	1	-	-
B13	PT22B	1	C	D6	PT27B	1	C	D6	PT31B	1	C	D6
A12	PT22A	1	T	-	PT27A	1	T	-	PT31A	1	T	-
B12	PT21B	1	C	D7	PT26B	1	C	D7	PT30B	1	C	D7
C12	PT21A	1	T	-	PT26A	1	T	-	PT30A	1	T	-
C11	PT20B	0	C	BUSY	PT25B	0	C	BUSY	PT29B	0	C	BUSY
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
B11	PT20A	0	T	CS1N	PT25A	0	T	CS1N	PT29A	0	T	CS1N
A11	PT19B	0	C	PCLKC0_0	PT24B	0	C	PCLKC0_0	PT28B	0	C	PCLKC0_0
A10	PT19A	0	T	PCLKT0_0	PT24A	0	T	PCLKT0_0	PT28A	0	T	PCLKT0_0
B10	PT18B	0	C	-	PT23B	0	C	-	PT27B	0	C	-
B9	PT18A	0	T	DQS	PT23A	0	T	DQS	PT27A	0	T	DQS
D11	PT17B	0	-	-	PT22B	0	-	-	PT26B	0	-	-
D10	PT16A	0	-	DOUT	PT21A	0	-	DOUT	PT25A	0	-	DOUT
A9	PT15B	0	C	-	PT20B	0	C	-	PT24B	0	C	-
-	GNDIO0	0	-	-	GNDIO0	0	-	-	GNDIO0	0	-	-
C8	PT15A	0	T	WRITEN	PT20A	0	T	WRITEN	PT24A	0	T	WRITEN
B8	PT14B	0	C	-	PT19B	0	C	-	PT23B	0	C	-
A8	PT14A	0	T	VREF1_0	PT19A	0	T	VREF1_0	PT23A	0	T	VREF1_0
C7	PT13B	0	C	-	PT18B	0	C	-	PT22B	0	C	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
L1	-	-	-	-	PL23A	7	T ³	-
M1	-	-	-	-	PL23B	7	C ³	-
M2	-	-	-	-	PL24A	7	-	-
L5	VCCP0	-	-	-	VCCP0	-	-	-
N2	GNDP0	-	-	-	GNDP0	-	-	-
N1	-	-	-	-	PL25B	6	-	-
P2	-	-	-	-	PL26A	6	T ³	-
P1	-	-	-	-	PL26B	6	C ³	-
M4	PL23A	6	T ³	-	PL27A	6	T ³	-
M3	PL23B	6	C ³	-	PL27B	6	C ³	-
R2	PL24A	6	T	PCLKT6_0	PL28A	6	T	PCLKT6_0
-	GNDIO6	6	-	-	GNDIO6	6	-	-
R1	PL24B	6	C	PCLKC6_0	PL28B	6	C	PCLKC6_0
N3	PL25A	6	T ³	-	PL29A	6	T ³	-
N4	PL25B	6	C ³	-	PL29B	6	C ³	-
M5	PL26A	6	-	-	PL30A	6	-	-
N5	PL27B	6	-	VREF1_6	PL31B	6	-	VREF1_6
T2	PL28A	6	T ³	DQS	PL32A	6	T ³	DQS
T1	PL28B	6	C ³	-	PL32B	6	C ³	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
U2	PL29A	6	T	LLM0_PLLT_IN_A	PL33A	6	T	LLM0_PLLT_IN_A
U1	PL29B	6	C	LLM0_PLLC_IN_A	PL33B	6	C	LLM0_PLLC_IN_A
P3	PL30A	6	T ³	-	PL34A	6	T ³	-
P4	PL30B	6	C ³	-	PL34B	6	C ³	-
P6	PL32A	6	T ³	-	PL36A	6	T ³	-
P5	PL32B	6	C ³	-	PL36B	6	C ³	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
V2	PL33A	6	T	-	PL37A	6	T	-
V1	PL33B	6	C	-	PL37B	6	C	-
W2	PL34A	6	T ³	-	PL38A	6	T ³	-
W1	PL34B	6	C ³	-	PL38B	6	C ³	-
R3	PL35A	6	-	VREF2_6	PL39A	6	-	VREF2_6
R4	PL36B	6	-	-	PL40B	6	-	-
R6	PL37A	6	T ³	DQS	PL41A	6	T ³	DQS
R5	PL37B	6	C ³	-	PL41B	6	C ³	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
Y2	PL38A	6	T	LLM0_PLLT_FB_A	PL42A	6	T	LLM0_PLLT_FB_A
Y1	PL38B	6	C	LLM0_PLLC_FB_A	PL42B	6	C	LLM0_PLLC_FB_A
T3	PL39A	6	T ³	-	PL43A	6	T ³	-
T4	PL39B	6	C ³	-	PL43B	6	C ³	-
W3	PL40A	6	T ³	-	PL44A	6	T ³	-
V3	PL40B	6	C ³	-	PL44B	6	C ³	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

Ball Number	LFXP15				LFXP20			
	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
AB19	PB37A	4	-	-	PB41A	4	-	-
AB20	PB38B	4	-	-	PB42B	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
V15	PB39A	4	T	DQS	PB43A	4	T	DQS
U15	PB39B	4	C	-	PB43B	4	C	-
Y15	PB40A	4	T	-	PB44A	4	T	-
W15	PB40B	4	C	-	PB44B	4	C	-
AA16	PB41A	4	T	-	PB45A	4	T	-
AA17	PB41B	4	C	-	PB45B	4	C	-
AA18	PB42A	4	T	-	PB46A	4	T	-
AA19	PB42B	4	C	-	PB46B	4	C	-
Y16	PB43A	4	T	-	PB47A	4	T	-
W16	PB43B	4	C	-	PB47B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA20	PB44A	4	T	-	PB48A	4	T	-
AA21	PB44B	4	C	-	PB48B	4	C	-
Y17	PB45A	4	-	-	PB49A	4	-	-
Y18	PB46B	4	-	-	PB50B	4	-	-
Y19	PB47A	4	T	DQS	PB51A	4	T	DQS
Y20	PB47B	4	C	-	PB51B	4	C	-
V16	PB48A	4	T	-	PB52A	4	T	-
U16	PB48B	4	C	-	PB52B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
U18	-	-	-	-	PB53A	4	T	-
V18	-	-	-	-	PB53B	4	C	-
W19	-	-	-	-	PB54A	4	T	-
W18	-	-	-	-	PB54B	4	C	-
U17	-	-	-	-	PB55A	4	T	-
V17	-	-	-	-	PB55B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
W17	-	-	-	-	PB56A	4	-	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
V19	PR43A	3	-	-	PR47A	3	-	-
U20	PR42B	3	C ³	-	PR46B	3	C ³	-
U19	PR42A	3	T ³	-	PR46A	3	T ³	-
V20	PR41B	3	C	-	PR45B	3	C	-
W20	PR41A	3	T	-	PR45A	3	T	-
T17	PR40B	3	C ³	-	PR44B	3	C ³	-
T18	PR40A	3	T ³	-	PR44A	3	T ³	-
T19	PR39B	3	C ³	-	PR43B	3	C ³	-
T20	PR39A	3	T ³	-	PR43A	3	T ³	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15C-3F484C	300	1.8/2.5/3.3V	-3	fpBGA	484	COM	15.5K
LFXP15C-4F484C	300	1.8/2.5/3.3V	-4	fpBGA	484	COM	15.5K
LFXP15C-5F484C	300	1.8/2.5/3.3V	-5	fpBGA	484	COM	15.5K
LFXP15C-3F388C	268	1.8/2.5/3.3V	-3	fpBGA	388	COM	15.5K
LFXP15C-4F388C	268	1.8/2.5/3.3V	-4	fpBGA	388	COM	15.5K
LFXP15C-5F388C	268	1.8/2.5/3.3V	-5	fpBGA	388	COM	15.5K
LFXP15C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	15.5K
LFXP15C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	15.5K
LFXP15C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20C-3F484C	340	1.8/2.5/3.3V	-3	fpBGA	484	COM	19.7K
LFXP20C-4F484C	340	1.8/2.5/3.3V	-4	fpBGA	484	COM	19.7K
LFXP20C-5F484C	340	1.8/2.5/3.3V	-5	fpBGA	484	COM	19.7K
LFXP20C-3F388C	268	1.8/2.5/3.3V	-3	fpBGA	388	COM	19.7K
LFXP20C-4F388C	268	1.8/2.5/3.3V	-4	fpBGA	388	COM	19.7K
LFXP20C-5F388C	268	1.8/2.5/3.3V	-5	fpBGA	388	COM	19.7K
LFXP20C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	19.7K
LFXP20C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	19.7K
LFXP20C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	19.7K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3E-3Q208C	136	1.2V	-3	PQFP	208	COM	3.1K
LFXP3E-4Q208C	136	1.2V	-4	PQFP	208	COM	3.1K
LFXP3E-5Q208C	136	1.2V	-5	PQFP	208	COM	3.1K
LFXP3E-3T144C	100	1.2V	-3	TQFP	144	COM	3.1K
LFXP3E-4T144C	100	1.2V	-4	TQFP	144	COM	3.1K
LFXP3E-5T144C	100	1.2V	-5	TQFP	144	COM	3.1K
LFXP3E-3T100C	62	1.2V	-3	TQFP	100	COM	3.1K
LFXP3E-4T100C	62	1.2V	-4	TQFP	100	COM	3.1K
LFXP3E-5T100C	62	1.2V	-5	TQFP	100	COM	3.1K

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3F484C	340	1.2V	-3	fpBGA	484	COM	19.7K
LFXP20E-4F484C	340	1.2V	-4	fpBGA	484	COM	19.7K
LFXP20E-5F484C	340	1.2V	-5	fpBGA	484	COM	19.7K
LFXP20E-3F388C	268	1.2V	-3	fpBGA	388	COM	19.7K
LFXP20E-4F388C	268	1.2V	-4	fpBGA	388	COM	19.7K
LFXP20E-5F388C	268	1.2V	-5	fpBGA	388	COM	19.7K
LFXP20E-3F256C	188	1.2V	-3	fpBGA	256	COM	19.7K
LFXP20E-4F256C	188	1.2V	-4	fpBGA	256	COM	19.7K
LFXP20E-5F256C	188	1.2V	-5	fpBGA	256	COM	19.7K

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3Q208I	136	1.8/2.5/3.3V	-3	PQFP	208	IND	3.1K
LFXP3C-4Q208I	136	1.8/2.5/3.3V	-4	PQFP	208	IND	3.1K
LFXP3C-3T144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	3.1K
LFXP3C-4T144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	3.1K
LFXP3C-3T100I	62	1.8/2.5/3.3V	-3	TQFP	100	IND	3.1K
LFXP3C-4T100I	62	1.8/2.5/3.3V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	5.8K
LFXP6C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	5.8K
LFXP6C-3Q208I	142	1.8/2.5/3.3V	-3	PQFP	208	IND	5.8K
LFXP6C-4Q208I	142	1.8/2.5/3.3V	-4	PQFP	208	IND	5.8K
LFXP6C-3T144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	5.8K
LFXP6C-4T144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3F388I	244	1.8/2.5/3.3V	-3	fpBGA	388	IND	9.7K
LFXP10C-4F388I	244	1.8/2.5/3.3V	-4	fpBGA	388	IND	9.7K
LFXP10C-3F256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	9.7K
LFXP10C-4F256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	9.7K

For Further Information

A variety of technical notes for the LatticeXP family are available on the Lattice website at www.latticesemi.com.

- LatticeECP/EC and LatticeXP sysIO Usage Guide (TN1056)
- Lattice ispTRACY Usage Guide (TN1054)
- LatticeECP/EC and LatticeXP sysCLOCK PLL Design and Usage Guide (TN1049)
- Memory Usage Guide for LatticeECP/EC and LatticeXP Devices (TN1051)
- LatticeECP/EC and XP DDR Usage Guide (TN1050)
- Power Estimation and Management for LatticeECP/EC and LatticeXP Devices (TN1052)
- LatticeXP sysCONFIG Usage Guide (TN1082)

For further information on interface standards refer to the following web sites:

- JEDEC Standards (LVTTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- PCI: www.pcisig.com